



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



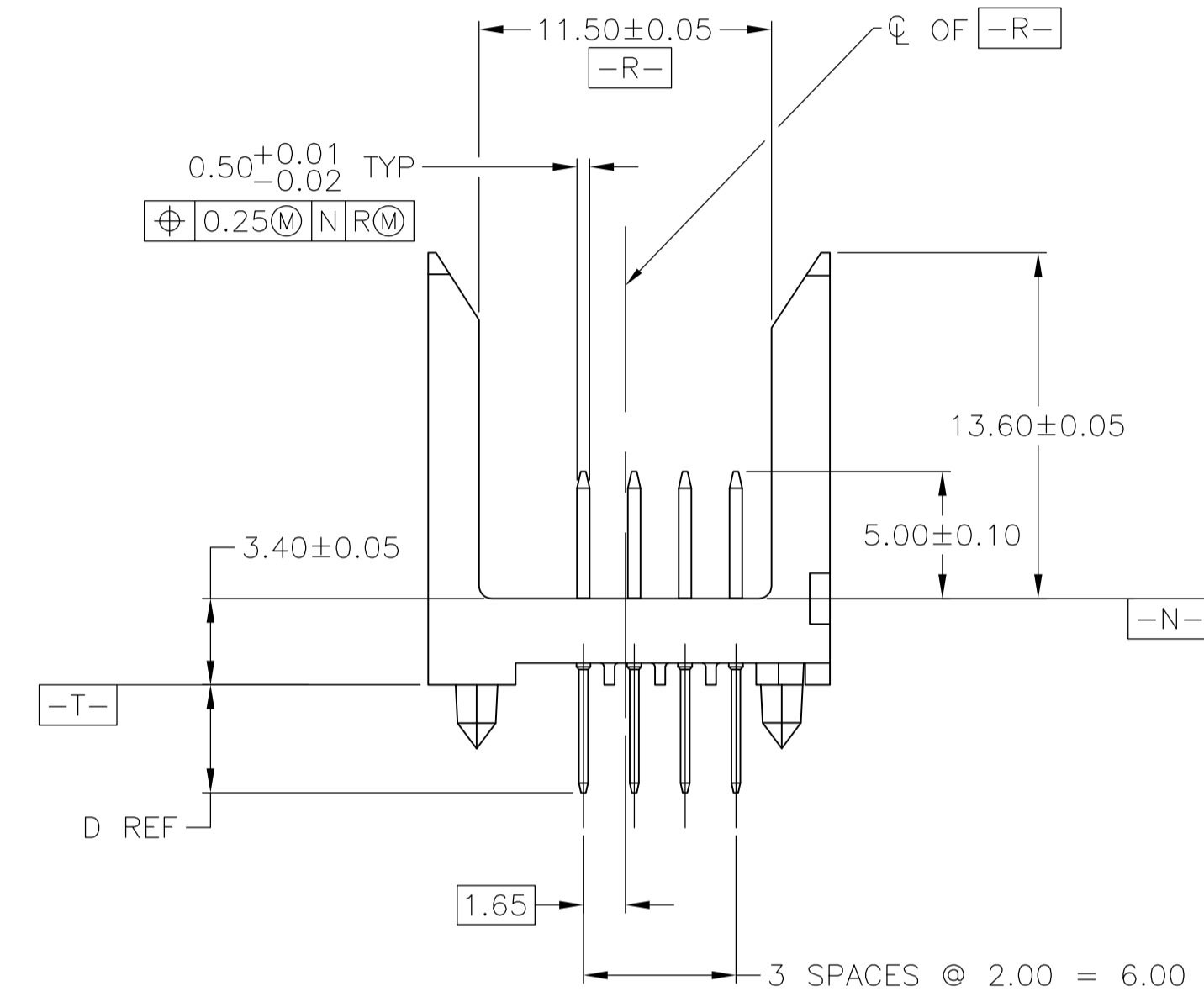
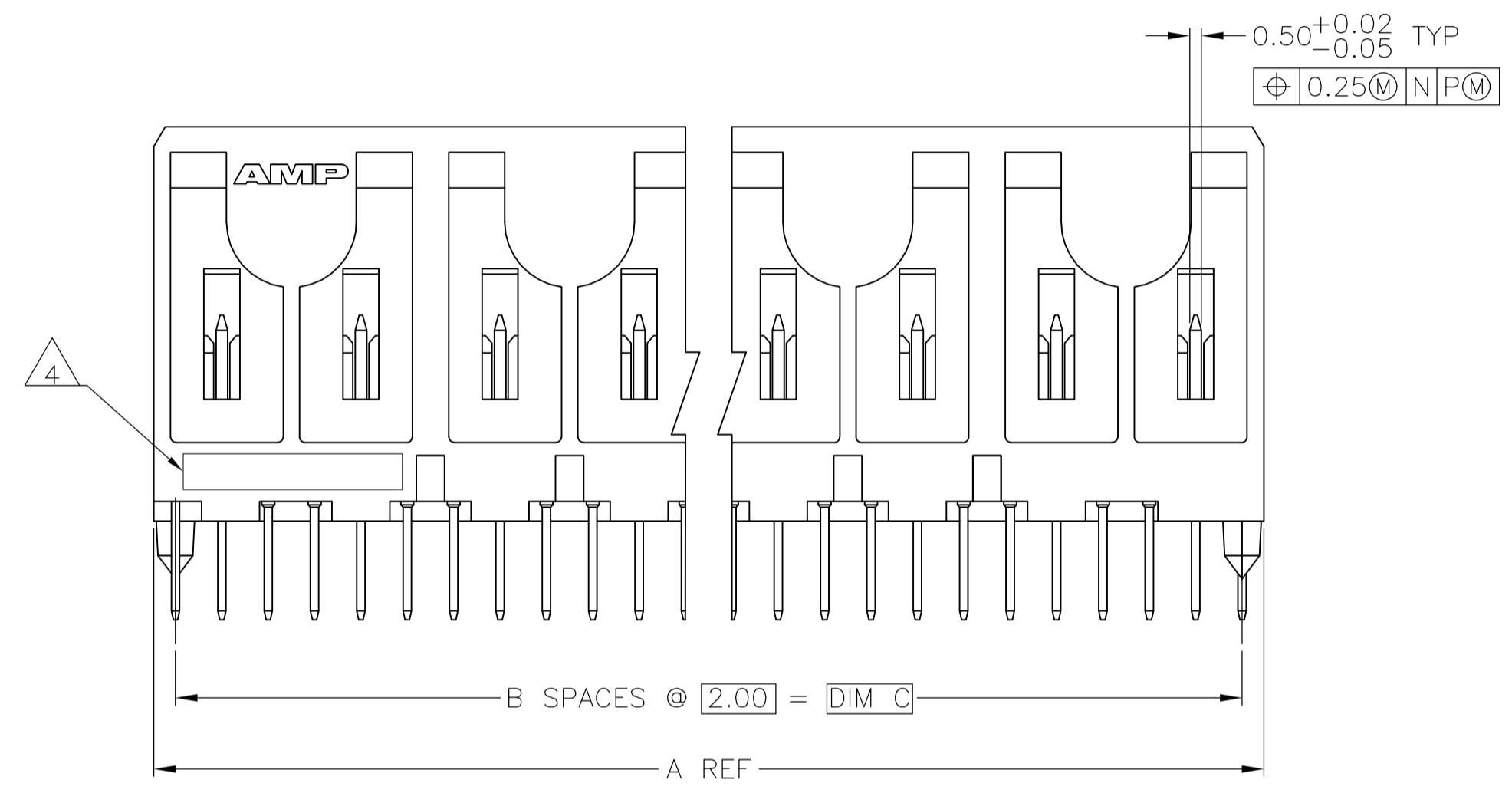
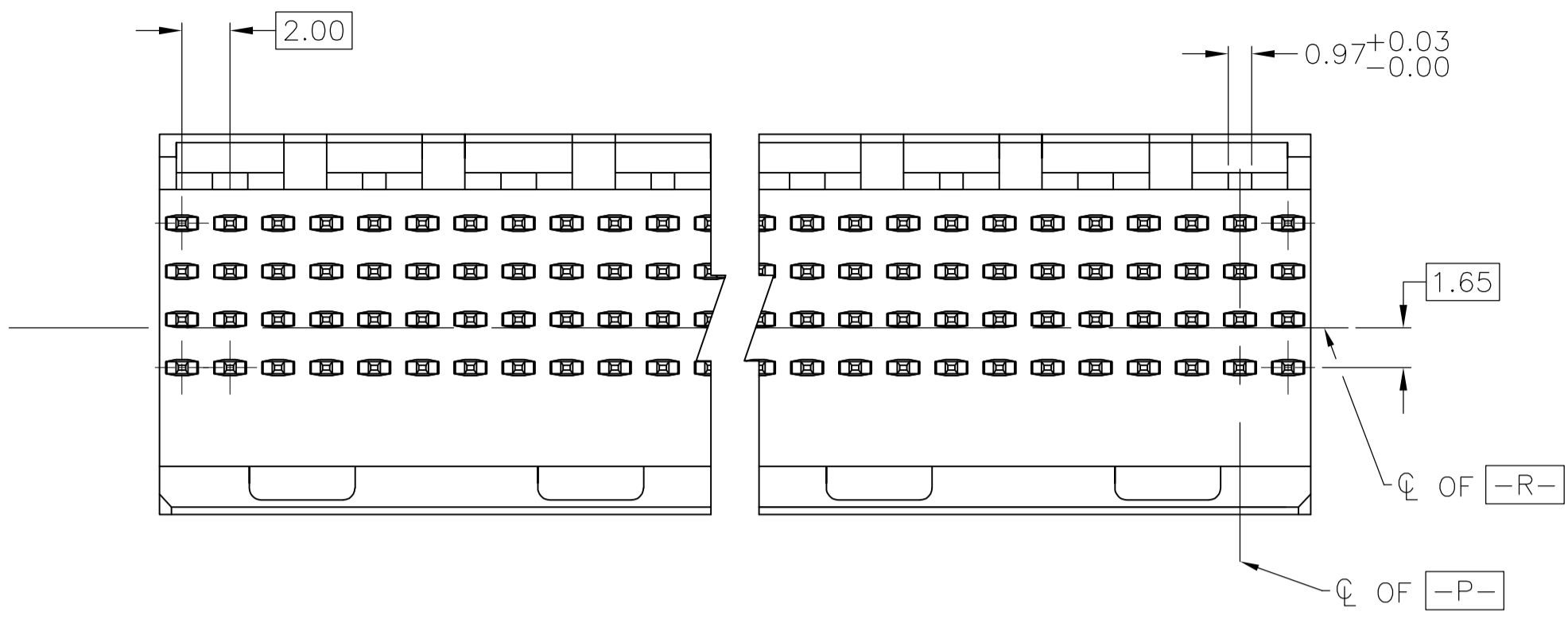
Contact us

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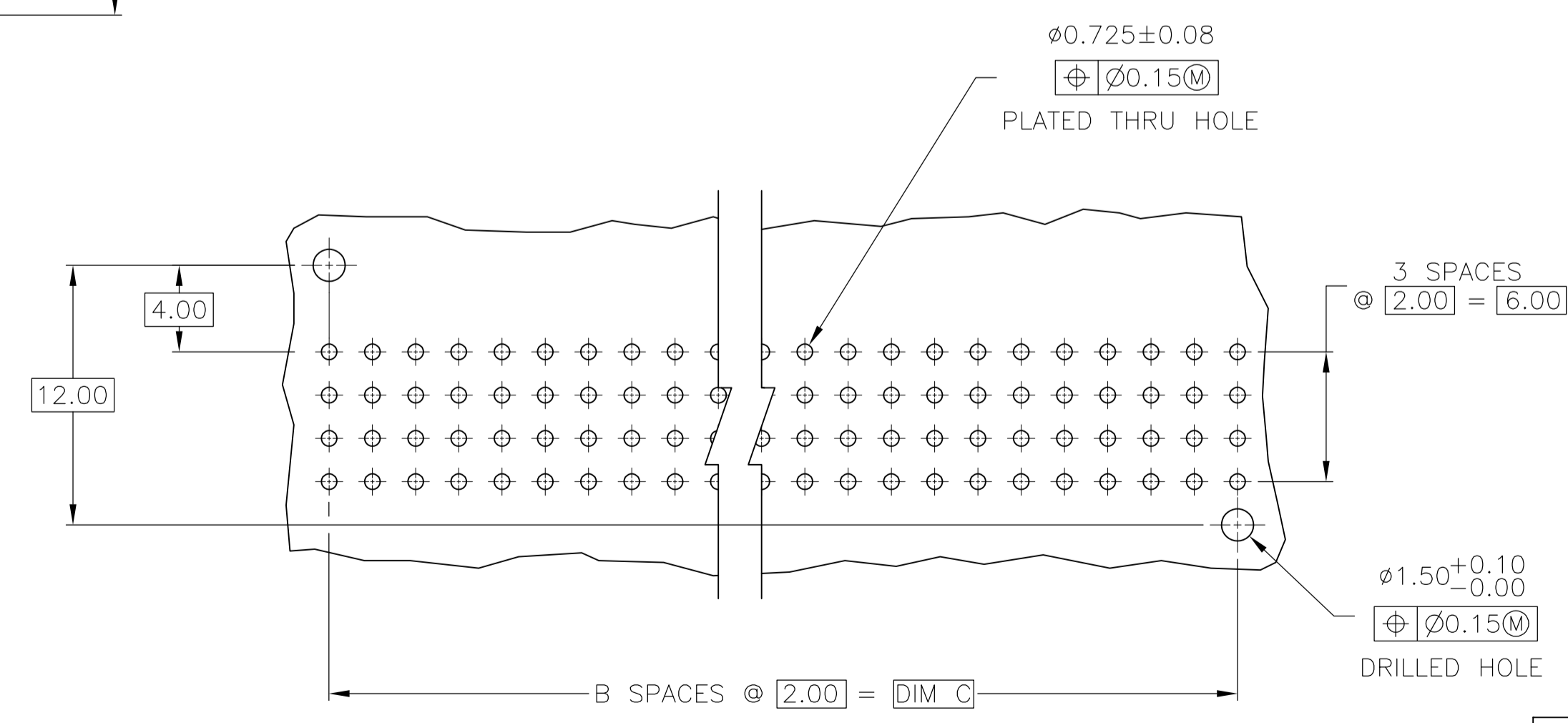
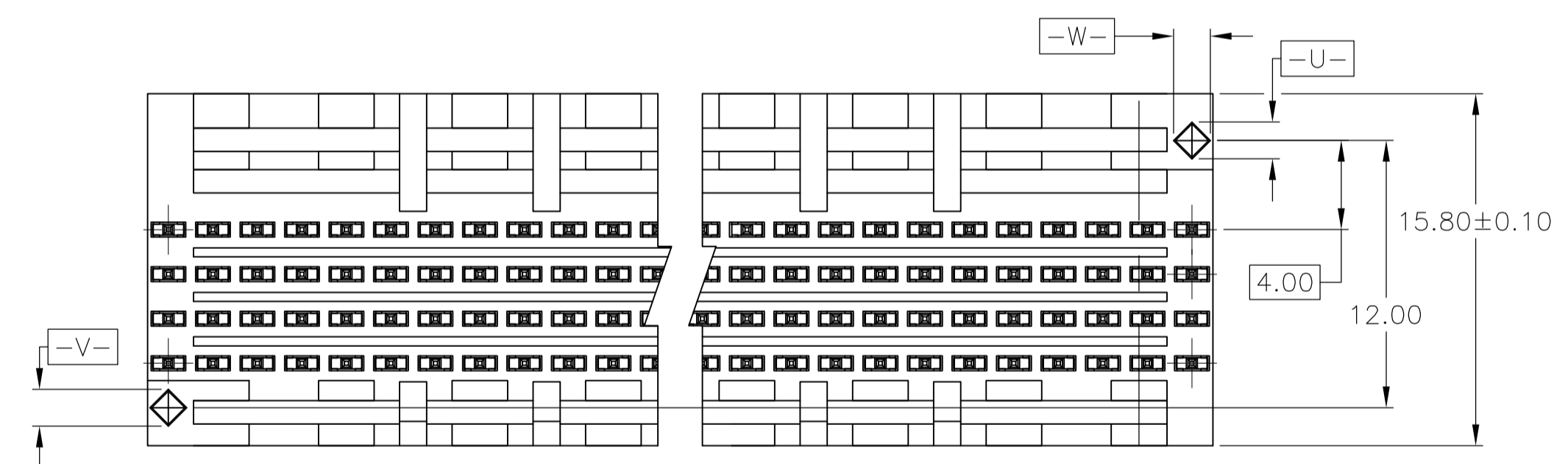
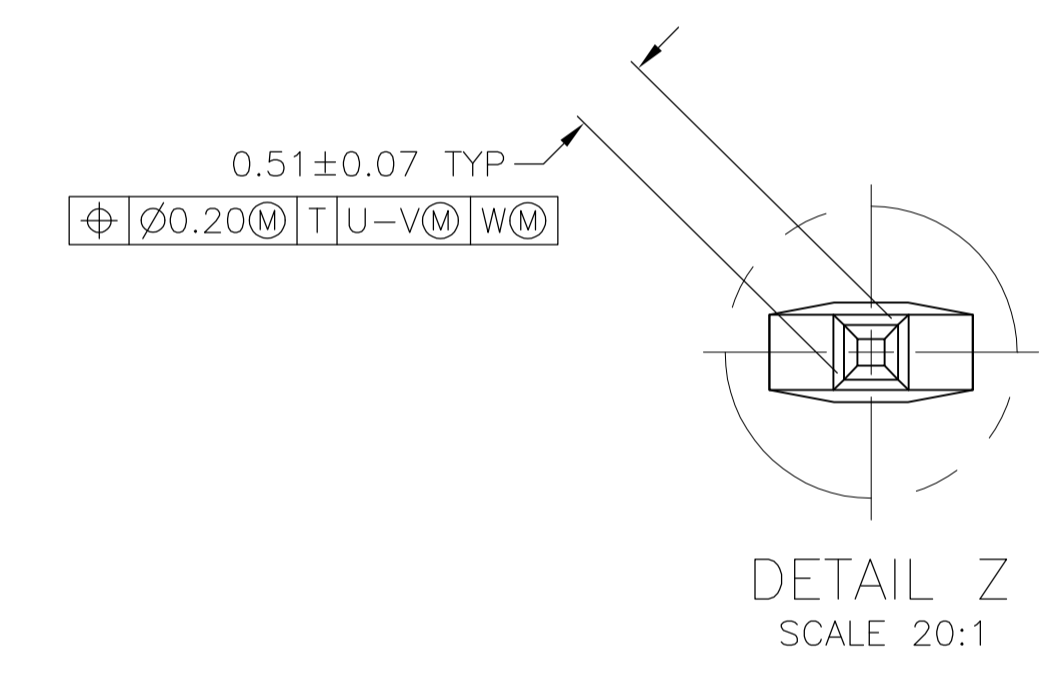
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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- 1 HOUSING MATERIAL: LIQUID CRYSTAL POLYMER PER ASTM D5138 LCP000 G30A 32250.
- 2 CONTACT MATERIAL: PHOSPHOR BRONZE.
- 3 CONTACT FINISH:
 UNDERPLATE (ENTIRE CONTACT):
 0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290.
 ON MATING SURFACES:
 CONFORMS TO ALL TESTING SPECIFIED FOR TELCORDIA UNCONTROLLED ENVIRONMENT.
 ON LEADS:
 0.00381 MIN TIN PER ASTM B 545 OVER UNDERPLATE.
 LUBRICATION (MIN MATING SURFACES):
 SURFACE CONDITIONER AFTER PLATING.
- 4 PART MARKING, LOCATED APPROXIMATELY AS SHOWN.
- 5 CONTACT FINISH:
 UNDERPLATE (ENTIRE CONTACT):
 0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290.
 ON MATING SURFACES:
 CONFORMS TO ALL TESTING SPECIFIED FOR TELCORDIA UNCONTROLLED ENVIRONMENT.
 ON LEADS:
 FLASH GOLD PER ASTM B 488 OVER UNDERPLATE.
 LUBRICATION (MIN MATING SURFACES):
 SURFACE CONDITIONER AFTER PLATING.



4.25	70.00	35	71.88	5	144	5536513-9
4.25	94.00	47	95.88	5	192	5536513-8
4.25	46.00	23	47.88	5	96	5536513-7
4.25	22.00	11	23.88	5	48	5536513-6
4.25	70.00	35	71.88	3	144	5536513-5
4.25	94.00	47	95.88	3	192	5536513-4
4.25	46.00	23	47.88	3	96	5536513-3
4.25	22.00	11	23.88	3	48	5536513-2
4.25	10.00	5	11.88	3	24	5536513-1
D	C	B	A	FINISH	NO OF POSN	NUMBER

RECOMMENDED CIRCUIT PATTERN PER IPC-D300 TYPE II, CLASS C (COMPONENT SIDE)

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	0 PLC ± -	1 PLC ± -	2 PLC ± -0.13	3 PLC ± -	4 PLC ± -	ANGLES ± -
MATERIAL	FINISH	WEIGHT	SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO	
1/2	3/5		A1	00779	5536513		

THIS DRAWING IS A CONTROLLED DOCUMENT. DIM: B, MCMMASTER, 31AUG04. CJK: R, WERTZ, 31AUG04. NAME: PIN ASSEMBLY, SIGNAL MODULE, Z-PACK 2mm FB 2mm, 4 ROW, 5.00mm MATING LENGTH, SOLDER END. APPLICATION SPEC: -. CUSTOMER DRAWING. SCALE: 4:1. SHEET: 1 OF 1. REV: 02.